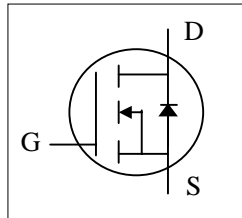




- ▼ Low Gate Charge
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant

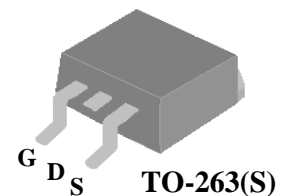
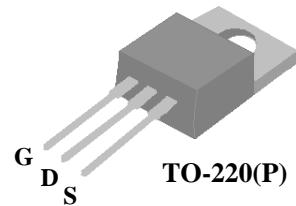


BV_{DSS}	75V
$R_{DS(ON)}$	11m Ω
I_D	80A

Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-263 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP75N07GP) are available for low-profile applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	75	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	80	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V	56	A
I_{DM}	Pulsed Drain Current ¹	300	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	156	W
	Linear Derating Factor	1.25	W/ $^\circ C$
E_{AS}	Single Pulse Avalanche Energy ³	450	mJ
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Thermal Resistance Junction-case	Max. 0.8	$^\circ C/W$
Rthj-a	Thermal Resistance Junction-ambient	Max. 62	$^\circ C/W$



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Electrical Characteristics @T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =1mA	75	-	-	V
ΔBV _{DSS} /ΔT _j	Breakdown Voltage Temperature Coefficient	Reference to 25°C, I _D =1mA	-	0.08	-	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =40A	-	-	11	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =40A	-	40	-	S
I _{DSS}	Drain-Source Leakage Current (T _j =25°C)	V _{DS} =75V, V _{GS} =0V	-	-	10	uA
	Drain-Source Leakage Current (T _j =150°C)	V _{DS} =60V, V _{GS} =0V	-	-	100	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V	-	-	±100	nA
Q _g	Total Gate Charge ²	I _D =40A	-	83	130	nC
Q _{gs}	Gate-Source Charge	V _{DS} =60V	-	10	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	51	-	nC
t _{d(on)}	Turn-on Delay Time ²	V _{DD} =40V	-	15	-	ns
t _r	Rise Time	I _D =30A	-	73	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =10Ω, V _{GS} =10V	-	340	-	ns
t _f	Fall Time	R _D =1.33Ω	-	200	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	4270	6830	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	690	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	320	-	pF
R _g	Gate Resistance	f=1.0MHz	-	1.8	2.7	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	T _j =25°C, I _S =40A, V _{GS} =0V	-	-	1.5	V
t _{rr}	Reverse Recovery Time	I _S =40A, V _{GS} =0V	-	90	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	-	235	-	nC

Notes:

- 1.Pulse width limited by safe operating area.
- 2.Pulse width ≤300us , duty cycle ≤2%.
- 3.Starting T_j=25°C , V_{DD}=50V , L=1mH , R_G=25Ω , I_{AS}=30A.

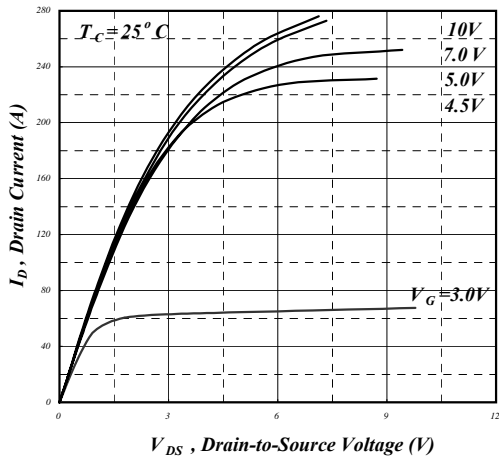


Fig 1. Typical Output Characteristics

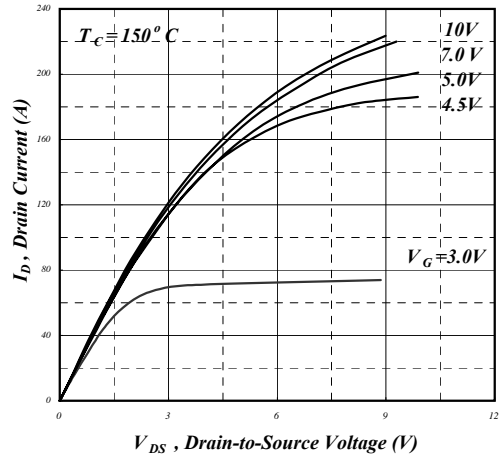


Fig 2. Typical Output Characteristics

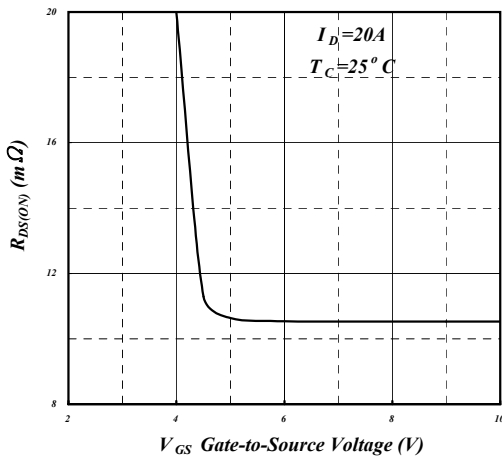


Fig 3. On-Resistance v.s. Gate Voltage

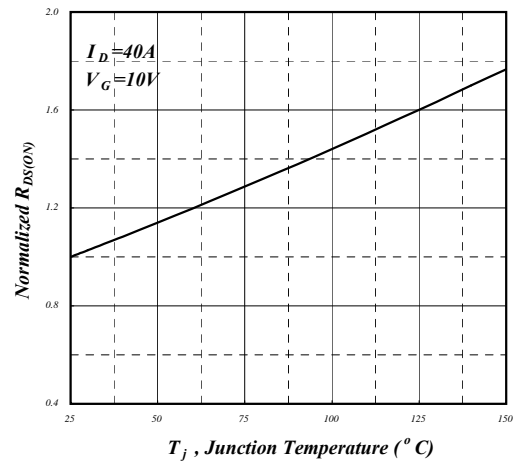


Fig 4. Normalized On-Resistance v.s. Junction Temperature

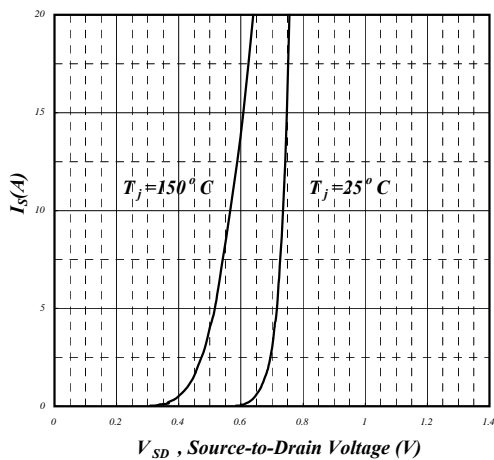


Fig 5. Forward Characteristic of Reverse Diode

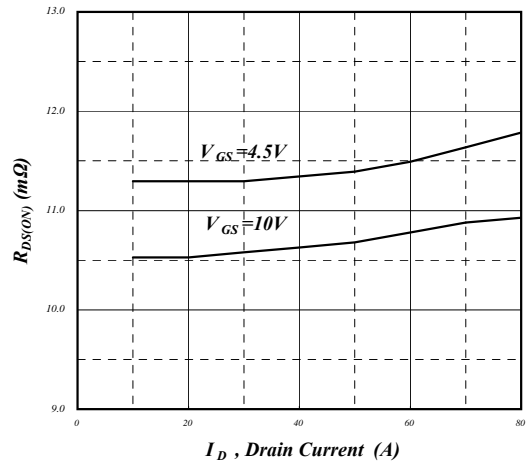


Fig 6. On-Resistance vs. Drain Current



AP75N07GP/S

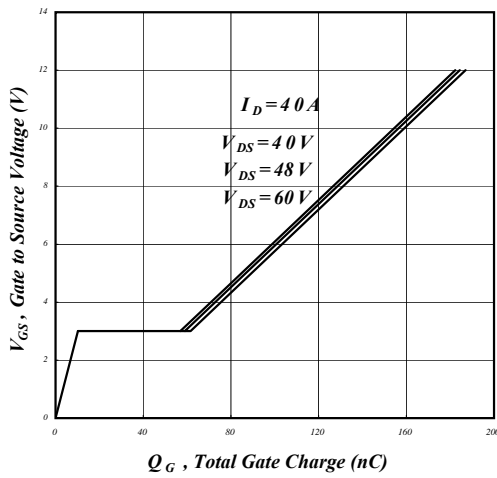


Fig 7. Gate Charge Characteristics

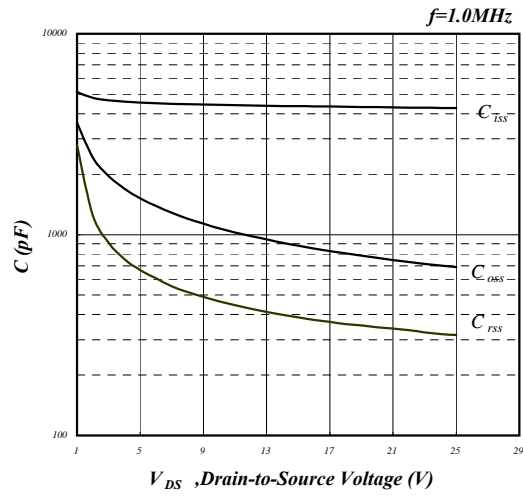


Fig 8. Typical Capacitance Characteristics

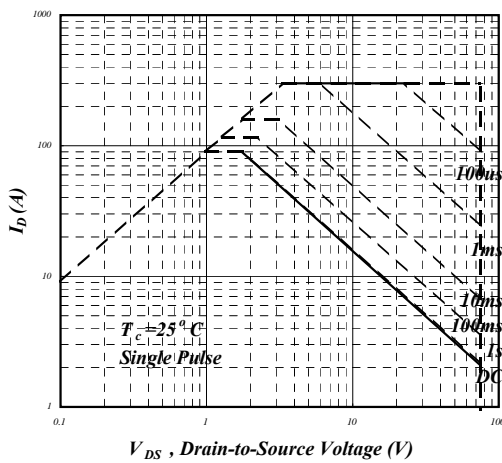


Fig 9. Maximum Safe Operating Area

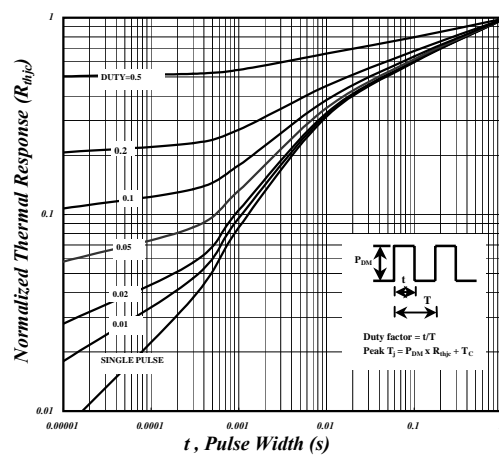


Fig 10. Effective Transient Thermal Impedance

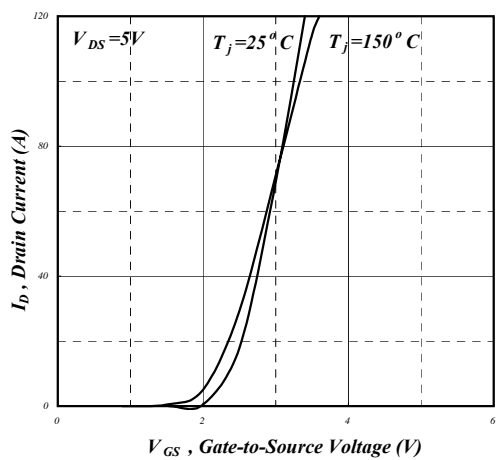


Fig 11. Transfer Characteristics

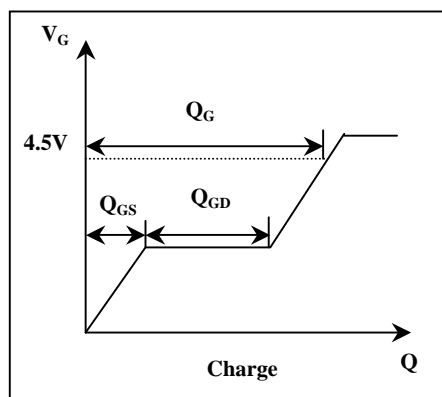
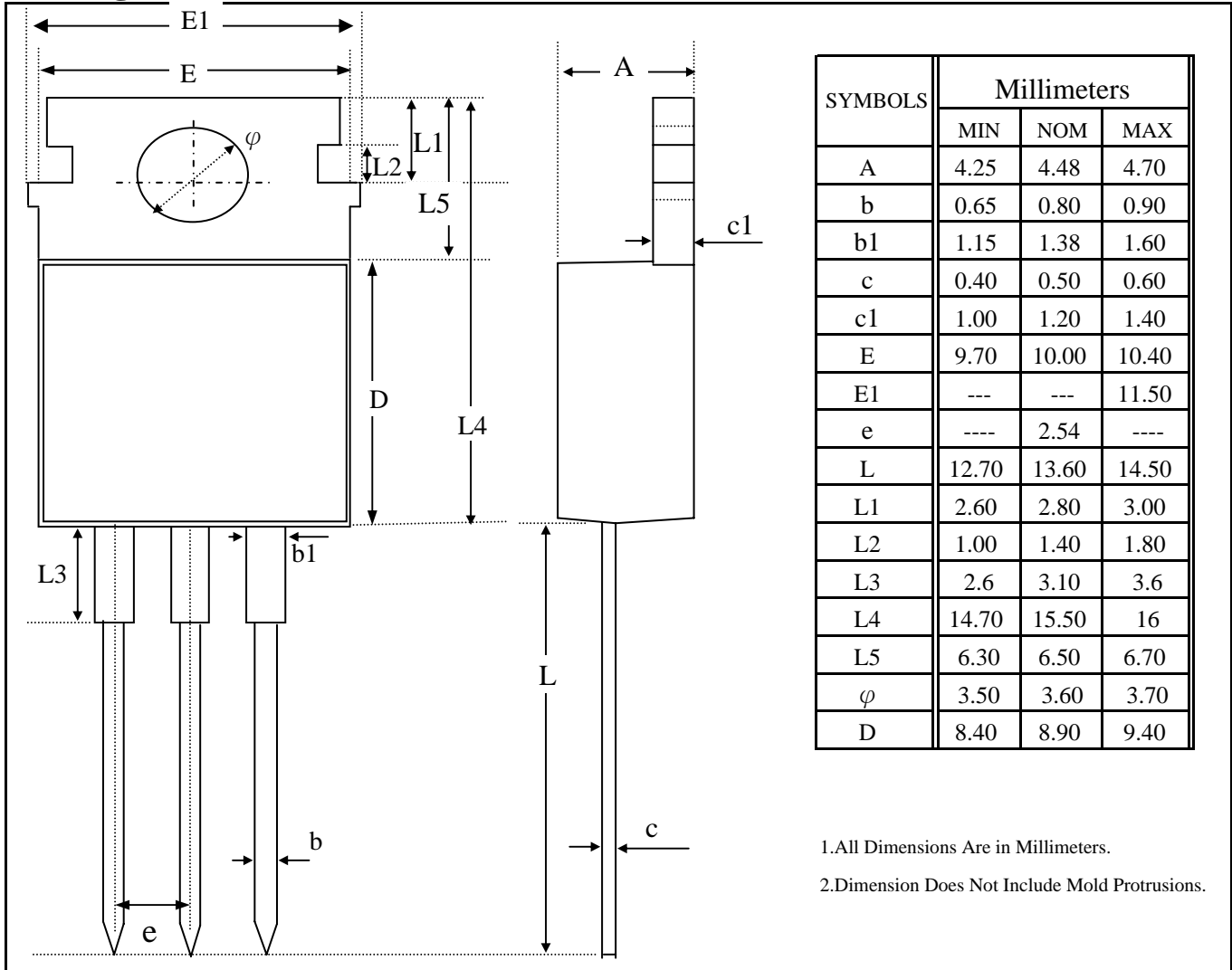


Fig 12. Gate Charge Waveform



Package Outline : TO-220 低壓



Part Marking Information & Packing : TO-220

